

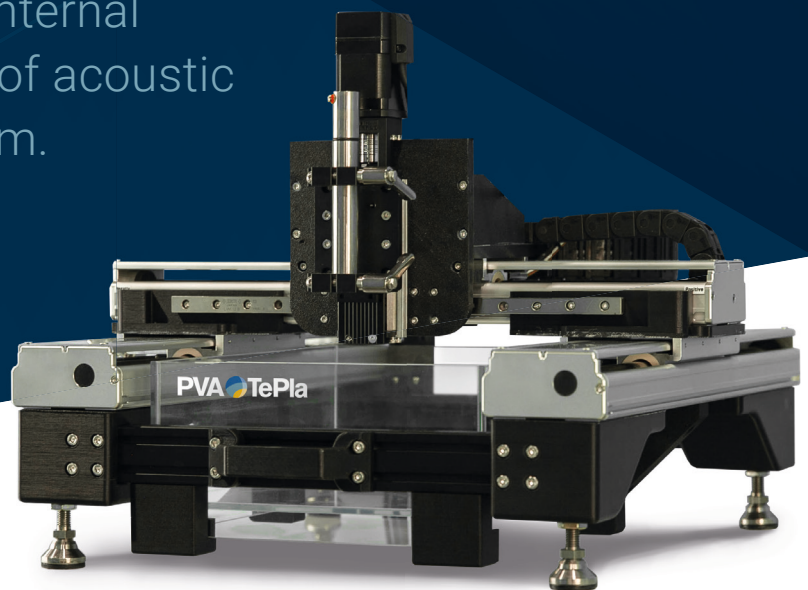
SCANNING ACOUSTIC MICROSCOPY

MINIVUE

ACOUSTIC PRECISION. ANYWHERE.

PVA TePla

The ultra-portable scanning acoustic microscope for non-destructive inspection in the lab, on the production floor, or in the field – reliably detecting voids, disbonds, cracks, delaminations, and internal defects. With the full power of acoustic microscopy in a 26 kg system.



FEATURES AT A GLANCE



Ready out of the case

Laptop with NVIDIA GPU, Thunderbolt Chassis, and Pulser-Receiver (5–150 MHz) included – fully self-contained, no external hardware required



Fully non-destructive process

Acoustic imaging preserves sample integrity – ideal for high-value and production-critical components



Full scanning mode portfolio

Pulse-Echo, A-Scan, B-Scan, C-Scan, TOF (Time of Flight), THK (Thickness) – comprehensive inspection capability in a compact system



Ultra-portable design

with transport/storage case for safe deployment



Application-specific transducers

Engineered for highest resolution – multiple transducer designs for enhanced scan capability across the full ultrasonic spectrum



ODIS Software – powered by intelligence

Advanced data-driven analysis



MORE INFORMATION? – GET IN CONTACT!

PVA TePla | OKOS

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PVA TePla

TECHNICAL PARAMETERS



Every detail matters. The MiniVUE is engineered for high-precision acoustic inspection — ideal for R&D departments, universities for prototypes/small volume testing and field testing of flat materials.

SPECIFICATIONS	
Scan Field	200 × 100 mm
Transducers	15, 35, 75, 110 MHz
Pulser-Receiver	5 to 150 MHz
ADC / Digitizer	8-bit, 1 GHz
Operating System	Windows 11 Pro
Computing	Laptop with NVIDIA GPU · Thunderbolt Chassis
Power Supply	120/240 VAC, 5 Amps, 1 PH
Water	Type 2 De-ionized
Dimensions	480 × 480 × 400 mm (WxDxH)
Weight	26 kg (incl. accessories)
Transport/Storage Case	32 × 23 × 19 in / 18.6 kg empty · 44 kg with system
SCANNING MODES	
Pulse-Echo	Single-transducer reflection imaging
A-Scan Waveforms	Real-time waveform display & capture
B-Scan	Cross-section images
C-Scan	Planar top-down images
TOF	Time of Flight mapping
THK	Thickness mapping
Measurements	■ Time Domain ■ Frequency Domain ■ Max. Peak Amplitude ■ Positive and Negative Peak Amplitud ■ Time of Flight to Peaks & Edges ■ End-User Signal Processing
SOFTWARE ODIS INSPECTION & ANALYSIS FEATURES	
User modes	■ Basic (user friendly) ■ Advanced (detailed analysis) ■ Off-line Analysis (virtual scanning)
Imaging	B-Scan & SLICE, 3D Imaging, Time-of-Flight & Thickness
Real-time	Void Gating, Real-time A-Scan Capture

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